

FIG. 1A

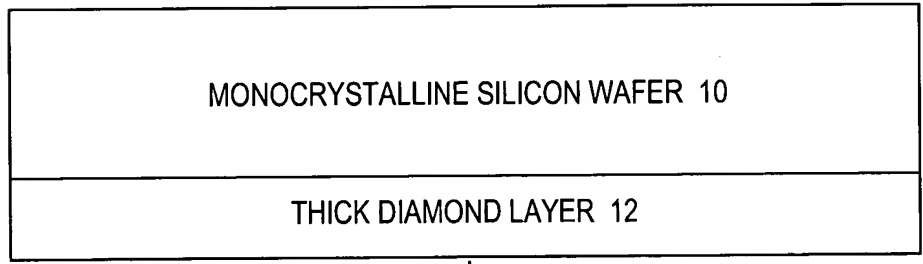


FIG. 1B

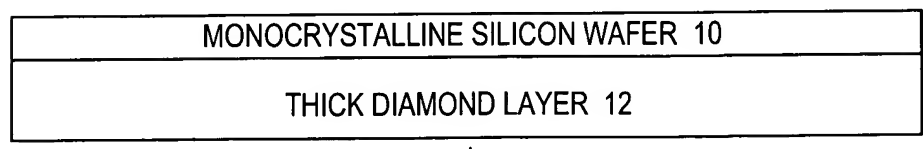


FIG. 1C

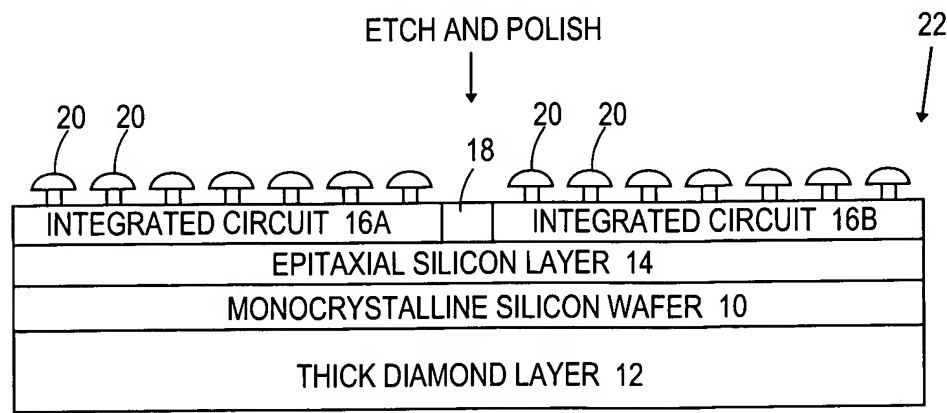
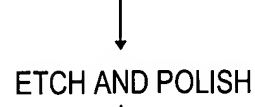


FIG. 1D

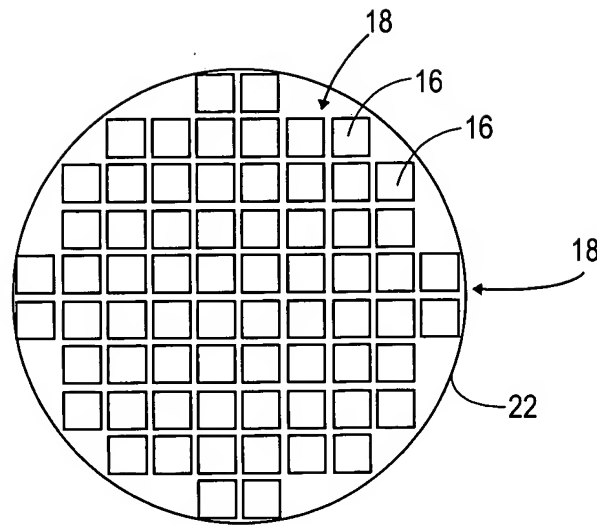


FIG. 1E

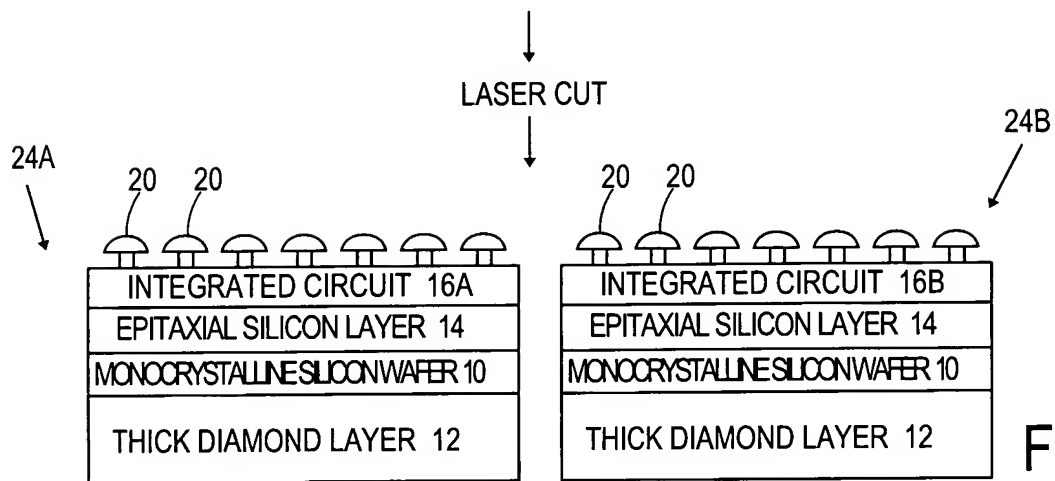


FIG. 1F

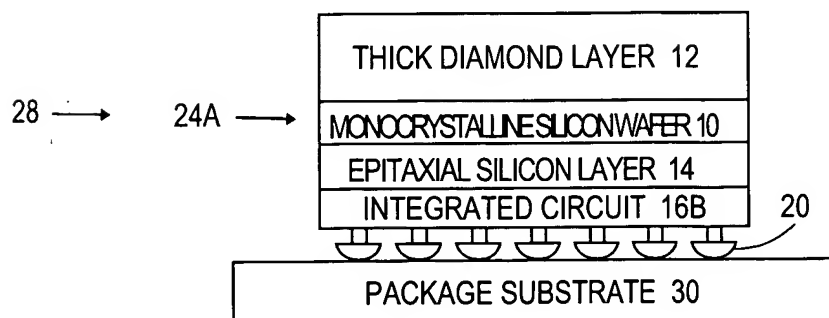


FIG. 1G

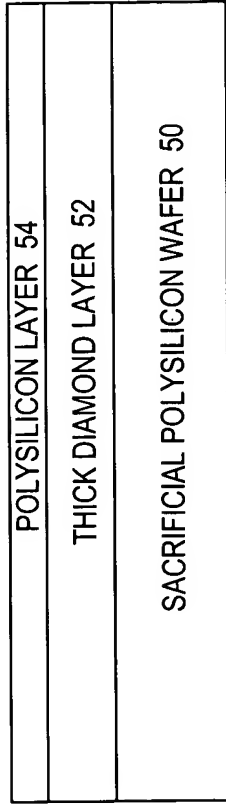


FIG. 2A

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FLIP
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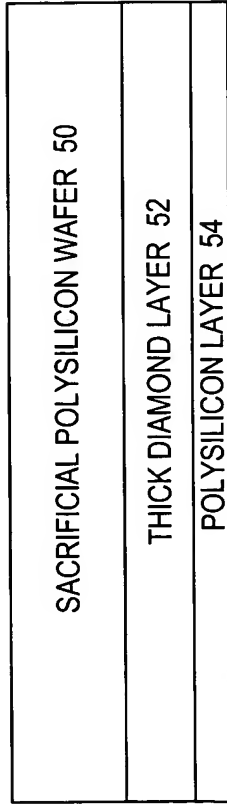
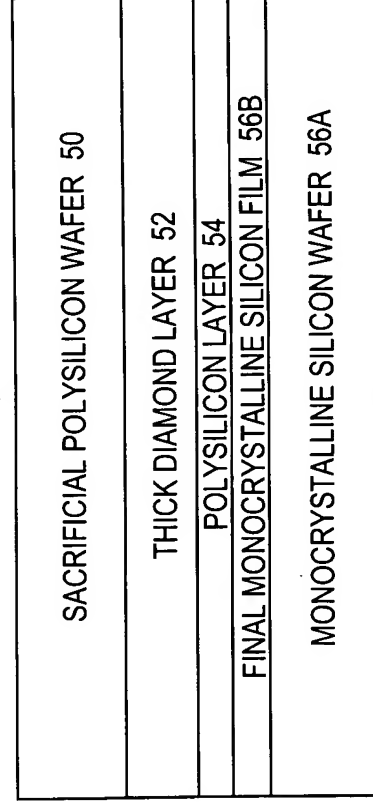


FIG. 2B

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SILICON BOND
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TO FIG. 2F

FIG. 2E

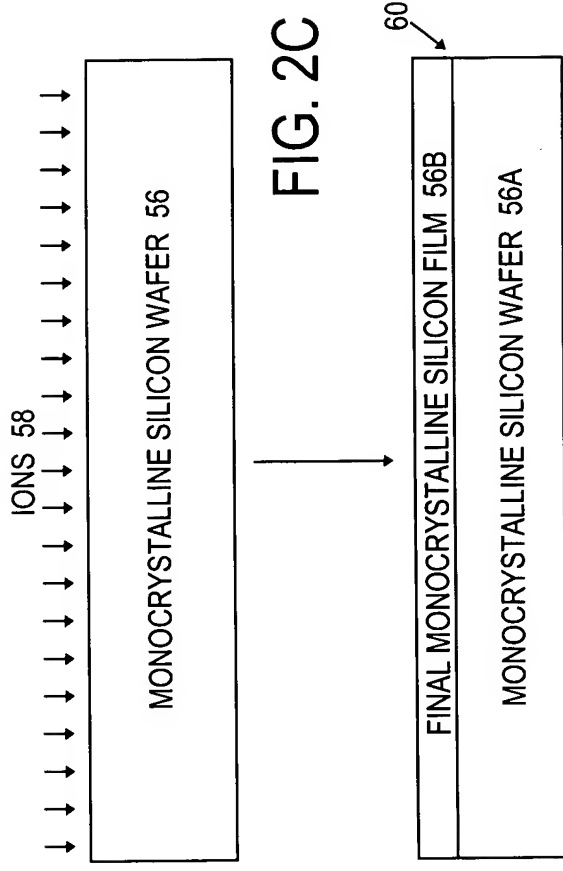


FIG. 2C

FIG. 2D

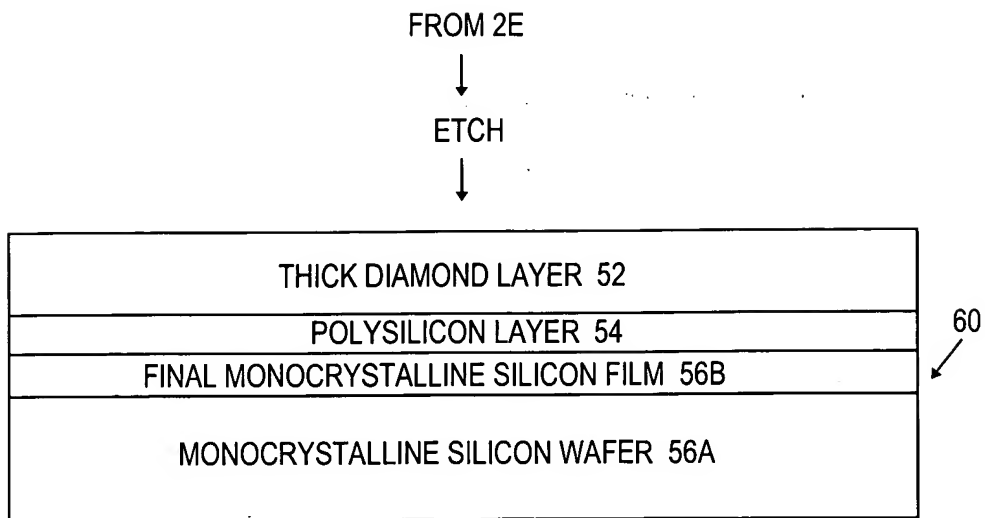


FIG. 2F

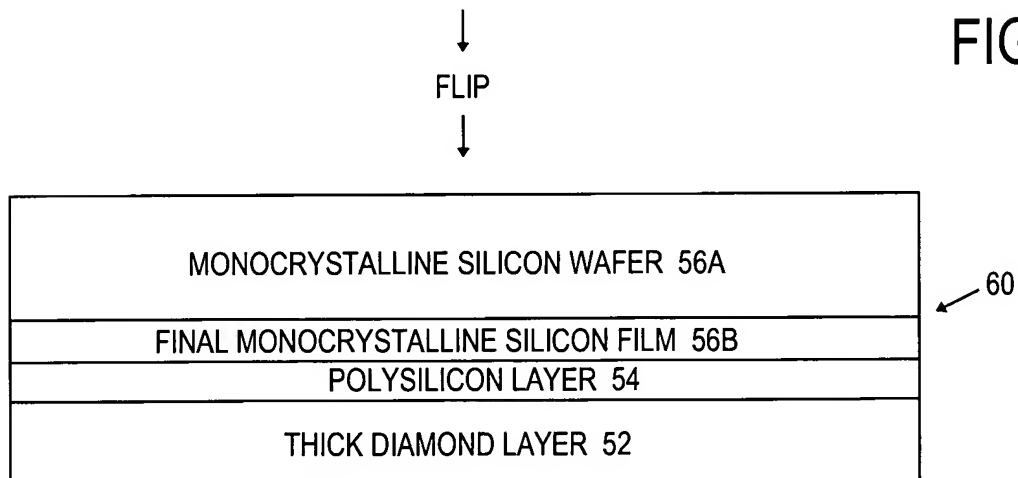


FIG. 2G

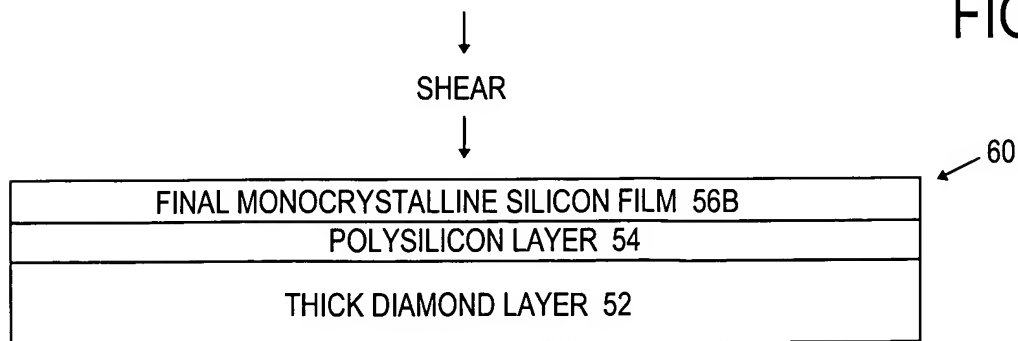


FIG. 2H

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ETCH AND POLISH

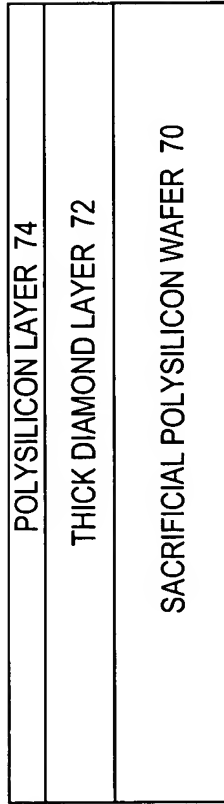


FIG. 3A

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FLIP
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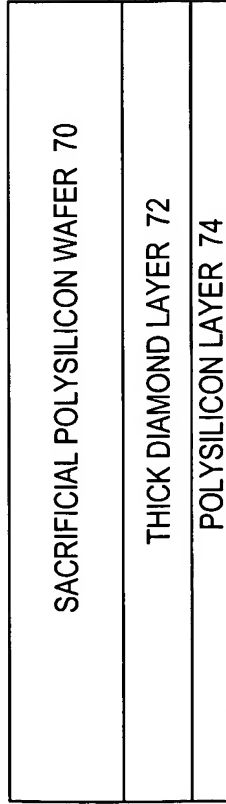


FIG. 3B

↓
SILICON BOND
↓

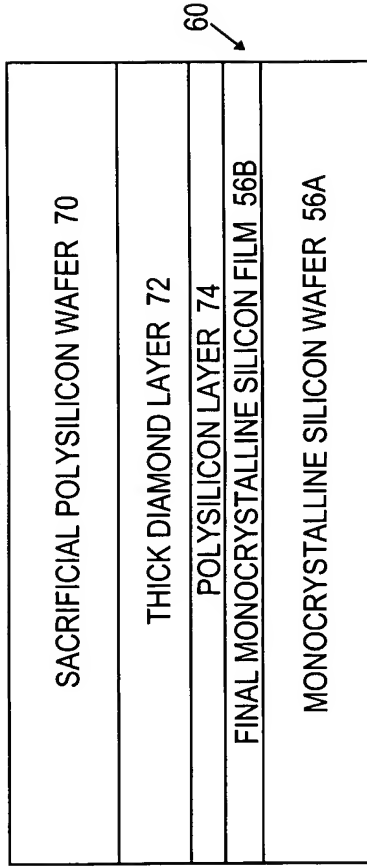


FIG. 3D

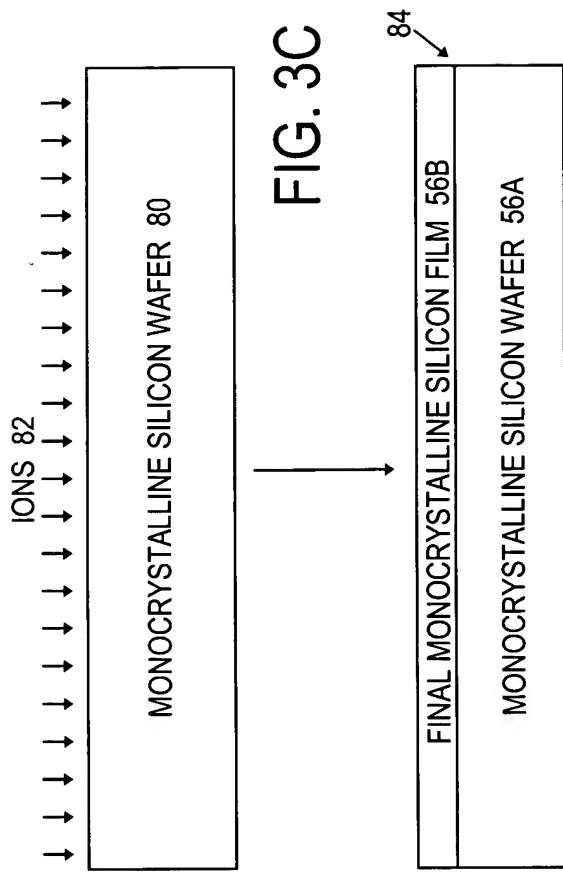


FIG. 3C

↓
TO FIG. 3F

FIG. 3E

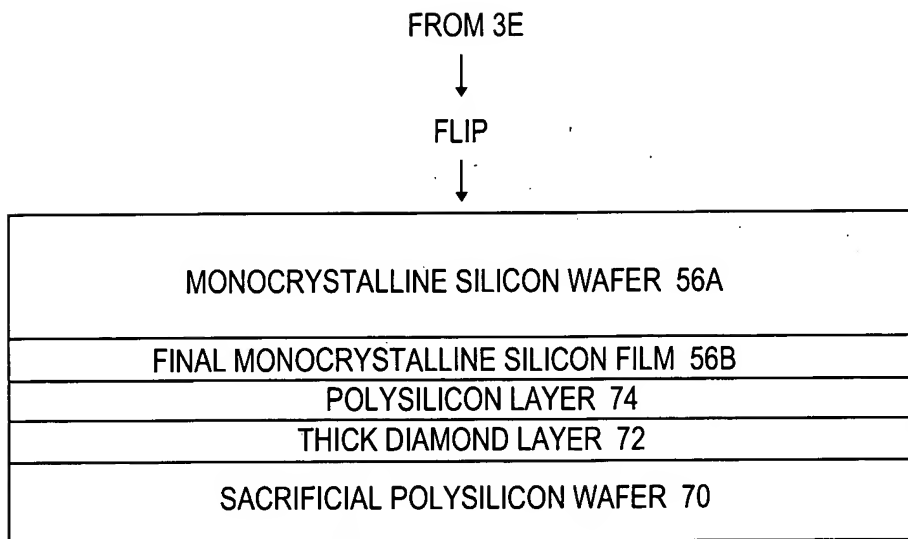


FIG. 3F

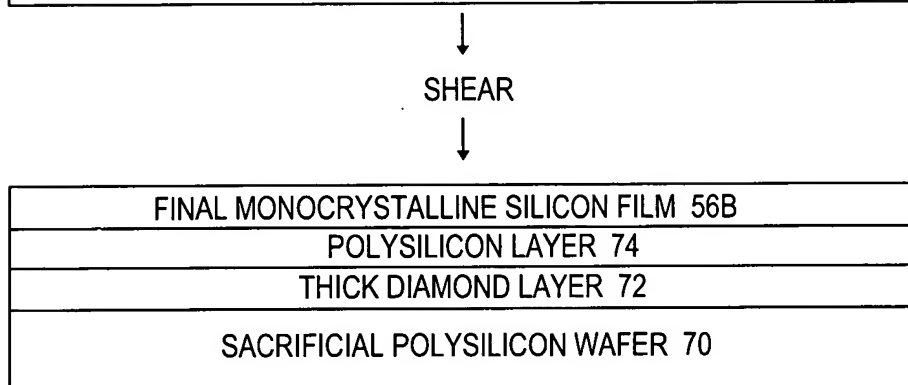


FIG. 3G

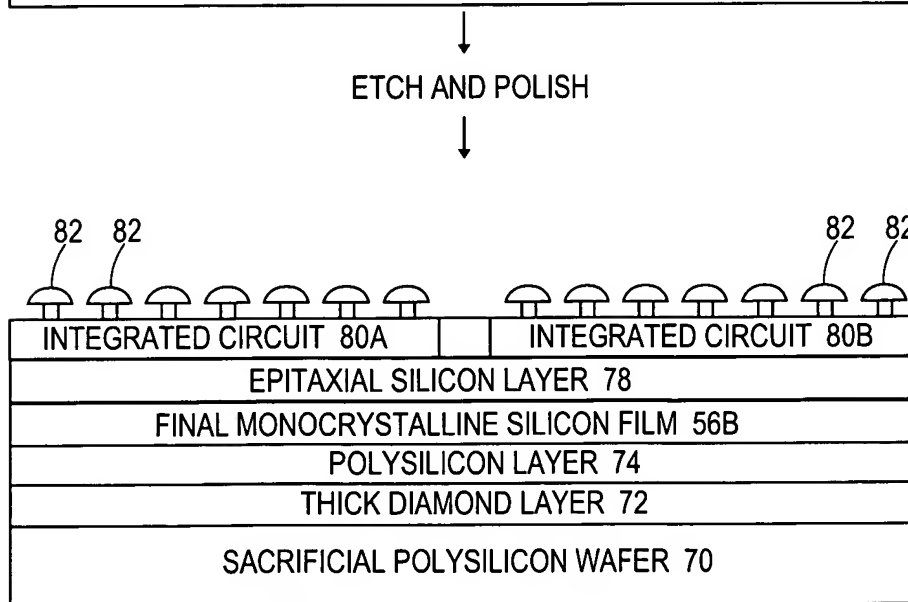


FIG. 3H

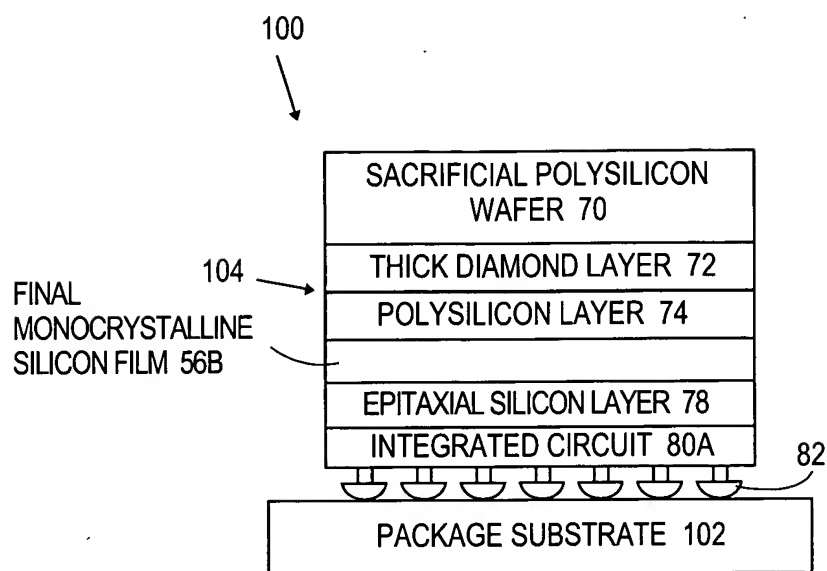


FIG. 3I

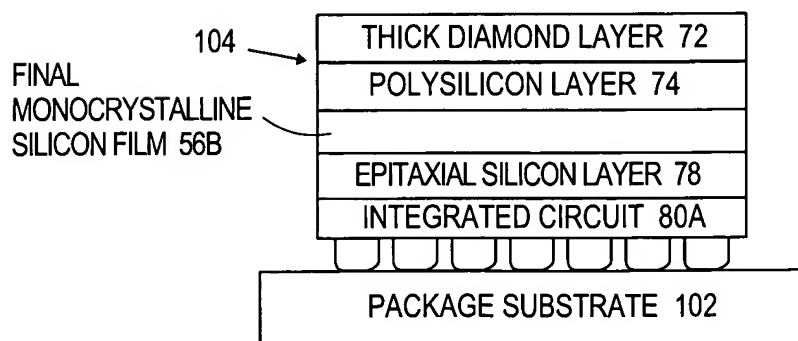


FIG. 3J